## PNP Epitaxial Silicon Transistor

# BSR16

#### **PNP General Purpose Amplifier**

- This Device Designed for Use as General Purpose Amplifier and Switches Requiring Collector Currents to 500 mA
- Sourced from Process 63
- See BCW68G for Characteristics

#### **ABSOLUTE MAXIMUM RATINGS**

 $(T_A = 25^{\circ}C, \text{ unless otherwise specified.})$ 

Symbol	Parameter	Value	Unit	
V <sub>CEO</sub>	Collector-Emitter Voltage	-60	V	
V <sub>CBO</sub>	Collector-Base Voltage	-60	V	
V <sub>EBO</sub>	Emitter-Base Voltage	-5.0	V	
Ι <sub>C</sub>	Collector Current – Continuous	-800	mA	
T <sub>J</sub> , T <sub>ST</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. These ratings are based on a maximum junction temperature of 150°C.
- 2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

#### THERMAL CHARACTERISTICS

(T<sub>A</sub> =  $25^{\circ}$ C, unless otherwise specified)

Symbol	Parameter	Max.	Unit
PD	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

3. Device mounted on FR-4 PCB 40 mm  $\times$  40 mm  $\times$  1.5 mm.

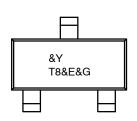


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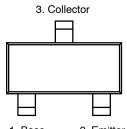


#### MARKING DIAGRAM



- &Y ON Semiconductor Logo
- T8 Specific Device Code
- &E Designates Space
- &G Date Code (Week)

#### **PIN ASSIGNMENT**



1. Base 2. Emitter

#### ORDERING INFORMATION

De	vice	Package	Shipping <sup>†</sup>
BSR16	3	SOT–23 (Pb–Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### BSR16

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C, unless otherwise specified)

Fall Time

t<sub>f</sub>

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARA	CTERISTICS				-	
BV <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	$I_{\rm C} = -10$ mA, $I_{\rm B} = 0$	-60			V
BV <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_{C} = -100 \ \mu A, \ I_{E} = 0$	-60			V
BV <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$	-5.0			V
I <sub>CBO</sub>	Collector Cut-off Current	V <sub>CB</sub> = -50 V V <sub>CB</sub> = -50 V, T <sub>A</sub> = 150°C			-10 -10	nA μA
I <sub>CEX</sub>	Collector Cut-off Current	$V_{CE} = -30$ V, $V_{EB} = -0.5$ V			-50	nA
I <sub>BEX</sub>	Reverse Base Current	$V_{CE} = -30$ V, $V_{EB} = -3.0$ V			-50	nA
ON CHARAG	CTERISTICS					
h <sub>FE</sub>	DC Current Gain		75 100 100 100 50	300		
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_{\rm C}$ = –150 mA, $I_{\rm B}$ = –15 mA $I_{\rm C}$ = –500 mA, $I_{\rm B}$ = –50 mA			-0.4 -1.6	V
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	I <sub>C</sub> = –150 mA, I <sub>B</sub> = –15 mA I <sub>C</sub> = –500 mA, I <sub>B</sub> = –50 mA			-1.3 -2.6	V
SMALL SIGI	NAL CHARACTERISTICS					
f <sub>T</sub>	Current Gain Bandwidth Product	$I_{C} = -50$ mA, $V_{CE} = -20$ V, f = 100 MHz, $T_{A} = 25^{\circ}C$	200			MHz
C <sub>cb</sub>	Output Capacitance	$V_{CB} = -10 \text{ V}, \text{ I}_{E} = 0, \text{ f} = 1.0 \text{ MHz}$			8.0	pF
C <sub>eb</sub>	Emitter-Base Capacitance	$V_{CB} = -2.0 \text{ V}, I_E = 0, f = 1.0 \text{ MHz}$			30	pF
SWITCHING	CHARACTERISTICS					
t <sub>on</sub>	Turn-On Time	V <sub>CC</sub> = -30 V, I <sub>C</sub> = -150 mA, I <sub>B1</sub> = -15 mA			45	ns
t <sub>d</sub>	Delay Time				10	ns
t <sub>r</sub>	Rise Time				40	ns
t <sub>off</sub>	Turn–Off Time	$V_{CC} = -6 \text{ V}, \text{ I}_{C} = -150 \text{ mA},$ $I_{B1} = I_{B2} = -15 \text{ mA}$			100	ns
t <sub>s</sub>	Storage Time				80	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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ns

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SOT-23 CASE 318BM **ISSUE A** DATE 01 SEP 2021 NOTES: UNLESS OTHERWISE SPECIFIED А D A) REFERENCE JEDEC REGISTRATION 3 TO-236, VARIATION AB, ISSUE H. В B) ALL DIMENSIONS ARE IN MILLIMETERS. C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. D) DIMENSIONING AND TOLERANCING PER E1 ASME Y14.5M - 2009. MILLIMETERS DIM SEE DETAIL A NOM. MIN. MAX. А 1.20 2 A1 0.00 0.05 0.10 (z) A2 0.93 REF b b 0.37 0 44 0.60 е ⊕ 0.20(M) A B 0.08 0.23 с 0.15 e1 D 2.72 2.92 3.12 F Е 2.10 2.40 2.70 E1 1.15 1.30 1.50 0.95 е 0.95 BSC (A2) A1 1.90 BSC e1 0.20 L --------0.10M C  $\square$ 1.40 L1 0.55 REF С z 0.29 REF GAGE PLANE 2.20 0.25 С 1 SEATING - 1.00 PLANE - (L1) -1.90 DETAIL A LAND PATTERN SCALE: 2X RECOMMENDATION \*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING GENERIC DETAILS, PLEASE DOWNLOAD THE ON **MARKING DIAGRAM\*** SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D. XXXM-. \*This information is generic. Please refer to device data sheet for actual part marking. XXX = Specific Device Code Pb-Free indicator, "G" or microdot "•", may Μ = Date Code or may not be present. Some products may = Pb-Free Package not follow the Generic Marking. Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON13784G Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** SOT-23 PAGE 1 OF 1

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